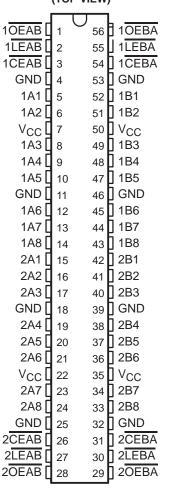
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- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- **Support Unregulated Battery Operation** Down to 2.7 V
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- **Typical V_{OLP} (Output Ground Bounce)** $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB Layout
- **Latch-Up Performance Exceeds 500 mA Per JESD 17**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- **Package Options Include Plastic Shrink** Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

SN54LVTH16543 . . . WD PACKAGE SN74LVTH16543... DGG OR DL PACKAGE (TOP VIEW)



description

The 'LVTH16543 devices are 16-bit registered transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch-enable (LEAB or LEBA) and output-enable (OEAB or OEBA) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable (CEAB) input must be low to enter data from A or to output data from B. If CEAB is low and LEAB is low, the A-to-B latches are transparent; a subsequent low-to-high transition of LEAB puts the A latches in the storage mode. With CEAB and OEAB both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar but requires using the $\overline{\sf CEBA}$, $\overline{\sf LEBA}$, and $\overline{\sf OEBA}$ inputs.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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description (continued)

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

The SN54LVTH16543 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LVTH16543 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE† (each 8-bit section)

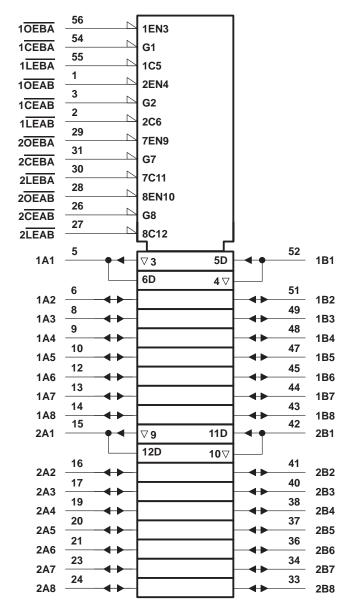
	INPUTS								
CEAB	LEAB	OEAB	Α	В					
Н	Χ	Х	Χ	Z					
Х	Χ	Н	Χ	Z					
L	Н	L	Χ	в ₀ ‡					
L	L	L	L	L					
L	L	L	Н	Н					

TA-to-B data flow is shown; B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.



[‡]Output level before the indicated steady-state input conditions were established

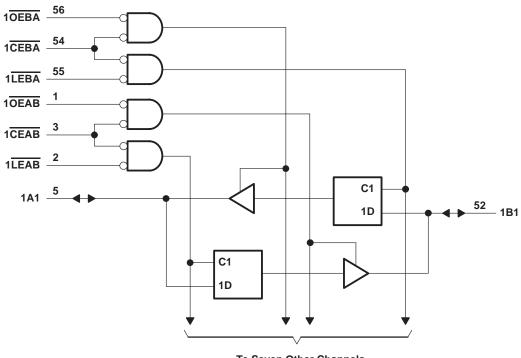
logic symbol†



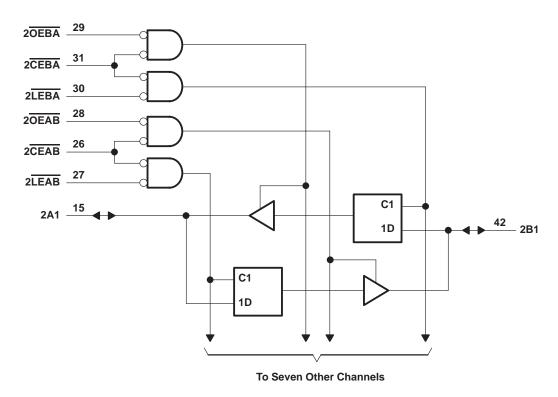
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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logic diagram (positive logic)



To Seven Other Channels





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high state, V _O (see Note 1)—0.5 V	to V_{CC} + 0.5 V
Current into any output in the low state, IO: SN54LVTH16543	96 mA
SN74LVTH16543	128 mA
Current into any output in the high state, IO (see Note 2): SN54LVTH16543	48 mA
SN74LVTH16543	64 mA
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 3): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T _{stq} –	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			SN54LVTI	116543	SN74LVTI	116543	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	2.7	3.6	2.7	3.6	V	
VIH	High-level input voltage	2	2	2		V	
V _{IL}	Low-level input voltage		0.8		0.8	V	
VI	Input voltage	4	5.5		5.5	V	
loн	High-level output current		7	-24		-32	mA
loL	Low-level output current		2	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	70,	10		10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200		μs/V
T _A	Operating free-air temperature	-55	125	-40	85	°C	

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD	AMETER	TEST 64	NUDITIONS	SN54	4LVTH16	5543	SN7	4LVTH16	5543	UNIT			
PAR	ANEIER	1531 CC	ONDITIONS	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNII			
VIK		$V_{CC} = 2.7 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V			
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0.2			VCC-0	.2					
\/		$V_{CC} = 2.7 \text{ V},$	IOH = -8 mA	2.4			2.4			V			
VOH		V _{CC} = 3 V	I _{OH} = -24 mA	2						V			
		∧CC = 2 ∧	I _{OH} = -32 mA				2						
		V _{CC} = 2.7 V	I _{OL} = 100 μA			0.2			0.2				
		VCC = 2.7 V	I _{OL} = 24 mA			0.5			0.5				
1			I _{OL} = 16 mA			0.4			0.4	V			
VOL		\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	I _{OL} = 32 mA			0.5			0.5	V			
		VCC = 3 V	I _{OL} = 48 mA			0.55							
	_		I _{OL} = 64 mA						0.55				
	Control inputs	V _{CC} = 3.6 V,	$V_I = V_{CC}$ or GND			\$ ±1			±1				
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V			10			10	1			
l _l	A or B ports‡		V _I = 5.5 V		Q ²	20		•	20	μΑ			
		V _{CC} = 3.6 V	$V_I = V_{CC}$		1	1			1	1			
			V _I = 0	– 5				– 5					
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V		0		±10		±100	μΑ			
		Vac - 2 V	V _I = 0.8 V	75			75						
I _I (hold)	A or B ports	VCC = 3 V	V _I = 2 V	– 75		- 75		μΑ					
		V _{CC} = 3.6 V§,	V _I = 0 to 3.6 V						±500				
lozpu		$\frac{V_{CC}}{OE} = 0$ to 1.5 V, $V_{O} = \frac{V_{CC}}{OE} = 0$ don't care	0.5 V to 3 V,			±100*			±100	μΑ			
lozpd		$\frac{V_{CC}}{OE}$ = 1.5 V to 0, V_{O} = $\frac{V_{CC}}{OE}$ = don't care	0.5 V to 3 V,			±100*			±100	μА			
		V _{CC} = 3.6 V,	Outputs high			0.19			0.19				
ICC		$I_{O} = 0$,	Outputs low			5			5	mA			
		$V_I = V_{CC}$ or GND	Outputs disabled			0.19			0.19				
ΔICC¶		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$, One input at $V_{CC} - 0.6 \text{ V}$ Other inputs at V_{CC} or GND				0.2			0.2	mA			
Ci		V _I = 3 V or 0			4			4		pF			
C _{io}		V _O = 3 V or 0			10			10		pF			

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ Unused pins at V_{CC} or GND

[§] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				5	SN54LV	ГН16543		S	N74LV	ГН16543		
				V _{CC} =		V _{CC} =	2.7 V	V _{CC} =		V _{CC} =	2.7 V	UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _W Pulse duration, LEAB or LEBA low				3.3		3.3		3.3		3.3		ns
	A or B before LEAB↑ or LEBA↑	Data high	0.5		0.5		0.5		0.5			
١.		LEAB↑ or LEBA↑	Data low	0.8		1.3		0.8		1.3		ns
t _{su}	Setup time	A or B before	Data high	0		0 %		0		0		115
		CEAB↑ or CEBA↑	Data low	0.6		1.1		0.6		1.1		
		A or B after	Data high	1.5	20	0.7		1.5		0.7		
۱.	th Hold time A or B after	LEAB↑ or LEBA↑	Data low	1.2	202	1.3		1.2		1.3		
l _t h			Data high	1.7	0	0.9		1.7		0.9		ns
	CEAB↑ or CEBA↑		Data low	1.6		1.8		1.6		1.8		

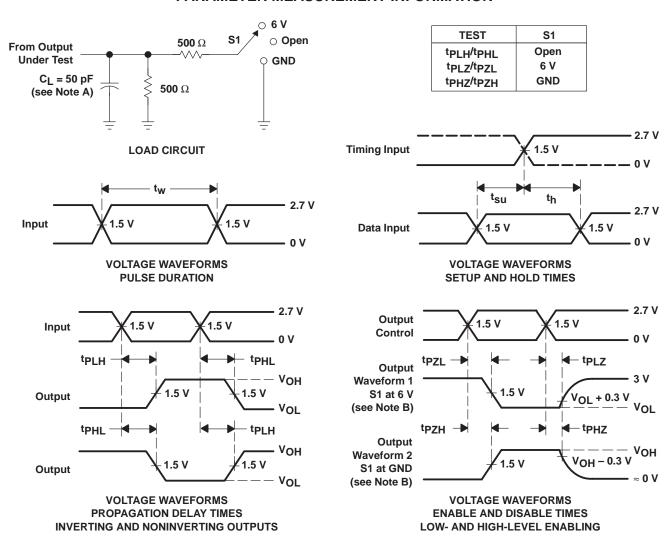
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

				SN54LV	ГН16543			SN74	LVTH16	5543			
PARAMETER	FROM TO (OUTPUT)		V _{CC} =		V _{CC} =	2.7 V		CC = 3.3 ± 0.3 V	٧	V _{CC} =	2.7 V	UNIT	
			MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX		
t _{PLH}	A or B	B or A	1.1	3.4		3.9	1.2	2.3	3.2		3.7	ns	
^t PHL	AOIB	BULK	1.1	3.4		3.9	1.2	2.1	3.2		3.7	115	
^t PLH	<u>LE</u>	A or B	1.2	4.1		5.1	1.3	2.5	3.9		4.9	ns	
^t PHL	LE	AUIB	1.2	4.1	141	5.1	1.3	2.3	3.9		4.9	118	
^t PZH	ŌĒ	A or B	1.2	4.5	14	5.6	1.3	2.8	4.3		5.4	20	
tPZL	OE	AUIB	1.2	4.5	Q	5.6	1.3	2.8	4.3		5.4	ns	
^t PHZ	ŌĒ	A or B	1.9	4.9		5.4	2	3.5	4.7		5.2	ns	
^t PLZ	OE	AOIB	1.9	4.6		4.7	2	3.3	4.4		4.5	115	
^t PZH	CE	A or B	1.2	4.7		5.8	1.3	3	4.5		5.6	20	
tPZL	CE	AUID	1.2	4.7		5.8	1.3	3	4.5		5.6	ns	
^t PHZ	CE	A or B	1.9	5.1		5.6	2	3.6	4.9		5.4	20	
^t PLZ	CE	AUIB	1.9	4.9		5.1	2	3.5	4.7		4.9	9 ns	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74LVTH16543DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVTH16543DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVTH16543DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16543DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16543DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16543DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVTH16543DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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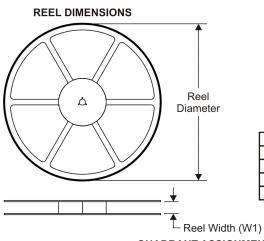
Enhanced Product: SN74LVTH16543-EP

NOTE: Qualified Version Definitions:

• Enhanced Product - Supports Defense, Aerospace and Medical Applications



TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH16543DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74LVTH16543DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH16543DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74LVTH16543DLR	SSOP	DL	56	1000	346.0	346.0	49.0

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

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